

**AMENDMENTS TO THE SPECIFICATION**

Please amend the title as follows:

Semiconductor Device Having ~~Heat-Conducting Plates~~ a Heat Conducting Plate

Please amend the paragraph beginning at page 1, line 5, as follows:

This application is a continuation application of U.S. Patent Application Serial No. 10/127,613, which was filed on April 23, 2003, and this application is based on and incorporates herein by reference Japanese Patent Application No. 2000-127516, which was filed on April 25, 2001.